

AMENDMENTS TO THE CLAIMS

Claim 1 (Withdrawn): A solder for joining microelectromechanical components, wherein the solder comprises a eutectic mixture of gold and bismuth.

Claim 2 (Previously Presented): A microelectromechanical component having at least one soldering layer for joining to at least one further component, which component includes at least one soldering layer made from a solder comprising at least one of a eutectic mixture of gold and bismuth and a bismuth layer for producing a soldered joint with to a gold layer.

Claim 3 (Withdrawn): The microelectromechanical component as claimed in claim 2, which includes soldering layers on opposite sides for joining to at least two further components.

Claim 4 (Original): The microelectromechanical component as claimed in claim 2, wherein at least one soldering layer, prior to the soldering operation, has a layer thickness of from 100 nm to 10 μ m.

Claim 5 (Currently Amended): A microelectromechanical device, wherein a soldered joint including a solder comprising a eutectic mixture of gold and bismuth joins at least two components, ~~wherein at least one component having one of an electrical functionality, a thermal functionality and a bonding functionality~~comprises at least two substrates joined together by said solder, and each substrate has a thermoelectric material arranged thereon.

Claim 6 (Currently Amended): The microelectromechanical device as claimed in claim 5, wherein ~~said soldered joint joins together two substrates, each substrate with thermoelectric material~~ is arranged thereon in the form of one of a Peltier cooler and a thermoelectric transducer.

Claim 7 (Withdrawn): The microelectromechanical device as claimed in claim 5, wherein at least one soldered joint joins a component to a laser diode circuit.

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